





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Grigg et al.

Serial No.: 10/688,354

Filed: October 17, 2003

For: THICK SOLDER MASK FOR CONFINING ENCAPSULANT MATERIAL OVER SELECTED LOCATIONS OF A SUBSTRATE AND ASSEMBLIES INCLUDING THE SOLDER MASK

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 2269-5216.1US

(99-0507.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 7, 2004 Date HAMPIN HARPIN

Rachael M. Harris
Name (Type/Print)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).





In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.





U.S. Patent Documents

U.S. Patent No.	Publication Date	Patentee
6,251,488	06/26/01	Miller et al.
6,259,962	07/10/01	Gothait
6,268,584	07/31/01	Keicher et al.
6,326,698	12/04/01	Akram
6,391,251	05/21/02	Keicher et al.
6,461,881	10/08/02	Farnworth et al.
6,506,671	01/14/03	Grigg
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6,548,897	04/15/03	Grigg
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6,611,053	08/26/03	Akram
6,630,365	10/07/03	Farnworth et al.
6,630,730	10/07/03	Grigg
6,649,444	11/18/03	Earnworth et al.

Other Documents

- U.S. Patent Application Publication 2002/0043711 A1 to Akram et al., dated April 18, 2002
- U.S. Patent Application Publication 2002/0105074 A1 to Akram et al., dated August 8, 2002
- U.S. Patent Application Publication 2002/0171177 A1 to Kritchman et al., dated November 21, 2002
- U.S. Patent Application Publication 2003/0022462 A1 to Farnworth et al., dated January 30, 2003





- U.S. Patent Application Publication 2003/0043360 A1 to Farnworth, dated March 6, 2003
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- U.S. Patent Application Publication 2003/0089999 A1 to Akram, dated May 15, 2003
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- U.S. Patent Application Publication 2003/0186496 A1 to Akram, dated October 2, 2003
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- U.S. Patent Application Publication 2003/0203612 A1 to Akram et al., dated October 30, 2003
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- MILLER et al., "Maskless Mesoscale Materials Deposition", Deposition Technology, September 2001, pages 20-22
- MILLER, "New Laser-Directed Deposition Technology", Microelectronic Fabrication, August 2001, page 16

Webpage, Objet Prototyping the Future, "Objet FullCure700 Series", 1 page

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- U.S. Patent Application No. 09/590,527, filed June 8, 2000, entitled "Structures for Stabilizing Semiconductor Devices Relative to Test Substrates and Methods for Fabricating the Stabilizers", inventor Salman Akram
- U.S. Patent Application No. 09/590,621, filed June 8, 2000, entitled "Stereolithographic Method and Apparatus for Fabricating Stabilizers for Flip-Chip Type Semiconductor Devices and Resulting Structures", inventor Akram et al.
- U.S. Patent Application No. 10/191,424, filed July 8, 2002, entitled "Semiconductor Devices with Permanent Polymer Stencil and Method for Manufacturing the Same", inventor Farnworth et al.
- U.S. Patent Application No. 10/370,755, filed February 20, 2003, entitled "Chip Scale Package Structures and Method of Forming Conductive Bumps Thereon", inventor Warren M. Farnworth
- U.S. Patent Application No. 10/641,471, filed August 14, 2003, entitled "Protective Structures for Bond Wires", inventor Salman Akram
- U.S. Patent Application No. 10/642,908, filed August 18, 2003, entitled "Solder Masks for Use on Carrier Substrates, Carrier Substrates and Semiconductor Device Assemblies Including Such Solder Masks, and Methods", inventor Tan et al.
- U.S. Patent Application No. 10/672,098, filed September 26, 2003, entitled "Apparatus and Methods for Use in Stereolithographic Processing of Components and Assemblies", inventor Warren M. Farnworth

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.



This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

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Date: January 7, 2004

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Enclosures: Form PTO-1449 or PTO/SB/08

Copy of documents cited

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PTO/SB/08A (10-01)

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O.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Akram

Farnworth

Grigg

Akram et al.

Akram

Farnworth et al.

Grigg

Earnworth et al.

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

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Substitute for form 1449A

Sheet

Complete if Known					
Application Number	10/688,354				
Filing Date	October 17, 2003				
First Named Inventor	Grigg et al.				
Group Art Unit	Unknown				
Examiner Name	Unknown				
Attorney Docket Number	5216.1US (99-0507.01/US)	J			

			U.S. PATENT D	OCUMENTS	
	G'a-	Document Number	Publication Date	Name of Patentee or Applicant of	Pages, Columns, Lines, Where Relevant
Examiner Initials *	Cite No.1	Number - Kind Code ² (if known)	MM-DD-YYYY	Cited Document	Passages or Relevant Figures Appear
		US- 6,251,488	06/26/01	Miller et al.	
		US- 6,259,962	07/10/01	Gothait	
		US- 6,268,584	07/31/01	Keicher et al.	
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FOREIGN PATENT DOCUMENTS						
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No. ¹	Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)	MM-DD-YYYY	Applicant of Cited Document	Where Relevant Passages or Relevant Figures Appear	T ⁶	
		-				
	Cite No. ¹	Cite Foreign Patent Document	Cite Foreign Patent Document Publication Date	Cite Foreign Patent Document Publication Date Applicant of Cited	Cite Foreign Patent Document Publication Date Name of Patentee or Applicant of Cited Where Relevant Passages or	

Examiner Signature	Date Considered	

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¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.





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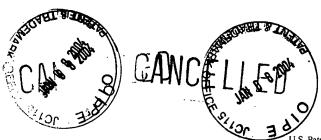
	Complete if Known	
Application Number	10/688,354	
Filing Date	October 17, 2003	
First Named Inventor	Grigg et al.	
Group Art Unit	Unknown	
Examiner Name	Unknown	
Attorney Docket Number	5216 1US (99-0507 01/US)	フ

	,	OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS	T
Examiner Initials *	Cite No. Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publicity and/or country where published.		
		U.S. Patent Application Publication 2002/0043711 A1 to Akram et al., dated April 18, 2002	
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Substitute for form 1449A/PTO Complete if Known Application Number 10/688,354 INFORMATION DISCLOSURE Filing Date October 17, 2003 STATEMENT BY APPLICANT First Named Inventor Grigg et al. Unknown Group Art Unit (use as many sheets as necessary) Examiner Name Unknown 5216 1US (99-0507 01/US)

	,	OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS	
Examiner Initials *	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
		U.S. Patent Application Publication 2003/0173665 A1 to Grigg, dated September 18, 2003	
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•		U.S. Patent Application Publication 2003/0180974 A1 to Akram, dated September 25, 2003	
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		OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS	
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		Webpage, Objet Prototyping the Future, "How it Works", 2 pages	
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		U.S. Patent Application No. 09/590,621, filed June 8, 2000, entitled "Stereolithographic Method and Apparatus for Fabricating Stabilizers for Flip-Chip Type Semiconductor Devices and Resulting Structures", inventor Akram et al.	
		U.S. Patent Application No. 10/191,424, filed July 8, 2002, entitled "Semiconductor Devices with Permanent Polymer Stencil and Method for Manufacturing the Same", inventor Farnworth et al.	
		U.S. Patent Application No. 10/370,755, filed February 20, 2003, entitled "Chip Scale Package Structures and Method of Forming Conductive Bumps Thereon", inventor Warren M. Farnworth	
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